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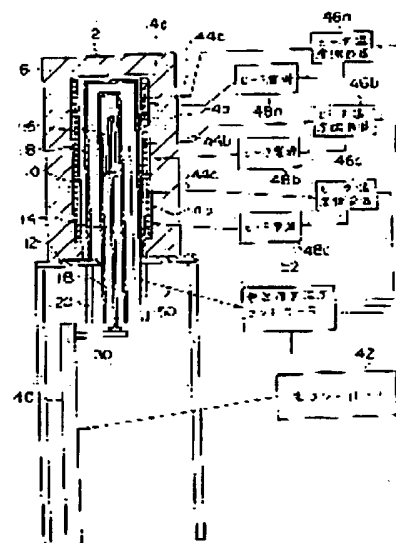
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## (54) DEVICE FOR HEAT TREATMENT OF SEMICONDUCTOR WAFER AND HEAT TREATING METHOD

## (57)Abstract:

**PURPOSE:** To uniformly heat a wafer continuously for a short period of time and to heat treat it in high quality and efficiency by incorporating a plurality of wafers simultaneously in a plurality of heating spaces, and heat treating them.

**CONSTITUTION:** A heat insulating material 6 is provided around two right and left flat platelike heaters 4a, 4b, 4c divided into a plurality of heating zones in a high temperature furnace 2, and a soaking tube 8 and a reaction tube 10 are provided inside the heaters. Two wafers 16 are inserted in a vertical state by placing on an inserting jig 14 inside the tube 10 from below the furnace 2. The jig 14 contains the wafers 16 in its heat treating chamber under the control of a main controller 42. After the heat treatment is finished, the jig 14 moves the wafers between coolers 20, and the wafers cooled for a predetermined period of time are removed by the movement of the jig 14. Each time a new wafer is inserted, the set temperature of the heater region of the center is altered to uniformly heat treat the wafer.



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